

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HAT2040R

Silicon N Channel Power MOS FET Power Switching

RENESAS

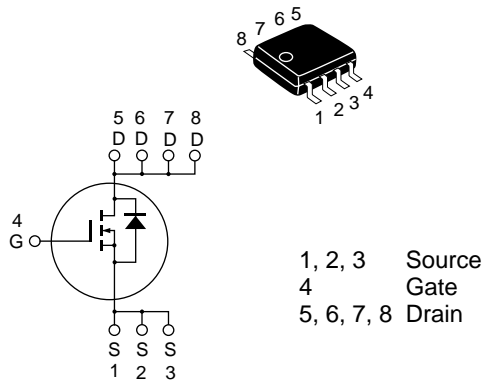
ADE-208-565D (Z)
5th. Edition
Mar. 2001

Features

- Low on-resistance
 $R_{DS(on)} = 6.2 \text{ m}\Omega$ typ
- Capable of 4 V gate drive
- Low drive current
- High density mounting

Outline

SOP-8



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	30	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	15	A
Drain peak current	$I_{D(pulse)}^{*1}$	120	A
Body to drain diode reverse drain current	I_{DR}	15	A
Channel dissipation	P_{ch}^{*2}	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \leq 10\mu s$, duty cycle $\leq 1\%$

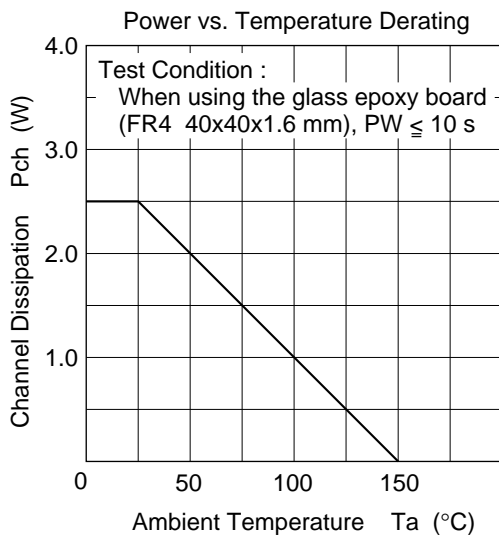
2. When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), $PW \leq 10s$

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10mA, V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	±0.1	μA	$V_{GS} = \pm 20V, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 30V, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.5	V	$V_{DS} = 10V, I_D = 1mA$
Static drain to source on state resistance	$R_{DS(on)}$	—	6.2	8.0	mΩ	$I_D = 8A, V_{GS} = 10V^{*1}$
	$R_{DS(on)}$	—	9.0	13.0	mΩ	$I_D = 8A, V_{GS} = 4V^{*1}$
Forward transfer admittance	$ y_{fs} $	18	30	—	S	$I_D = 8A, V_{DS} = 10V^{*1}$
Input capacitance	C_{iss}	—	4400	—	pF	$V_{DS} = 10V$
Output capacitance	C_{oss}	—	1100	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	500	—	pF	$f = 1MHz$
Total gate charge	Q_g	—	90	—	nc	$V_{DD} = 10V$
Gate to source charge	Q_{gs}	—	15	—	nc	$V_{GS} = 10V$
Gate to drain charge	Q_{gd}	—	18	—	nc	$I_D = 15A$
Turn-on delay time	$t_{d(on)}$	—	110	—	ns	$V_{GS} = 4V, I_D = 8A$
Rise time	t_r	—	410	—	ns	$V_{DD} \cong 10V$
Turn-off delay time	$t_{d(off)}$	—	200	—	ns	
Fall time	t_f	—	230	—	ns	
Body to drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_F = 15A, V_{GS} = 0^{*1}$
Body to drain diode reverse recovery time	t_{rr}	—	55	—	ns	$I_F = 15A, V_{GS} = 0$ $diF/dt = 20A/\mu s$

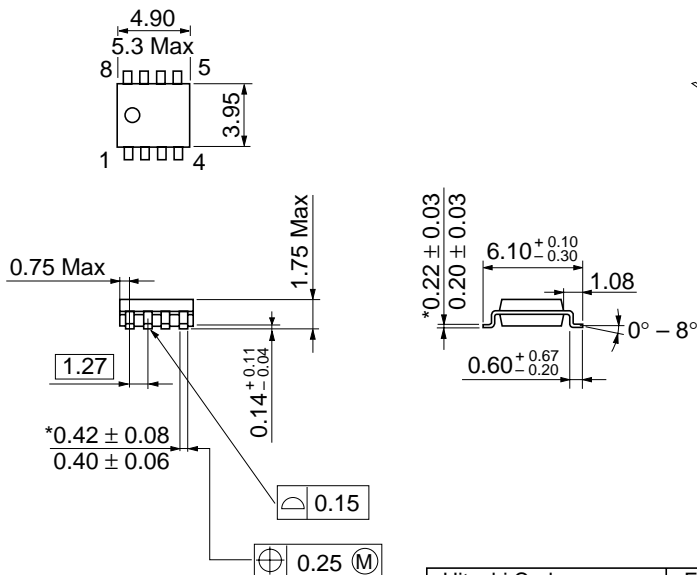
Note: 1. Pulse test

Main Characteristics



Package Dimensions

As of January, 2001
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-8DA
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.085 g

Cautions

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